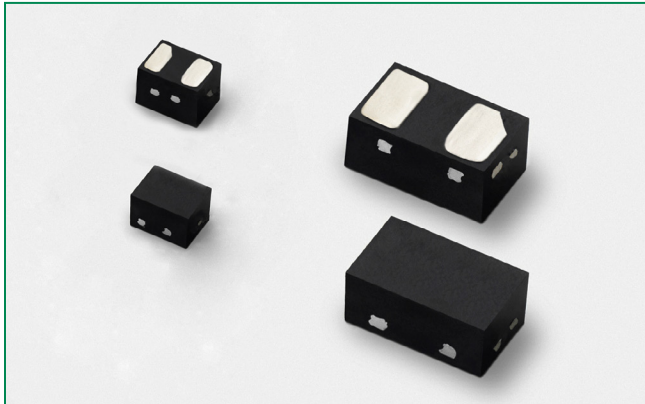




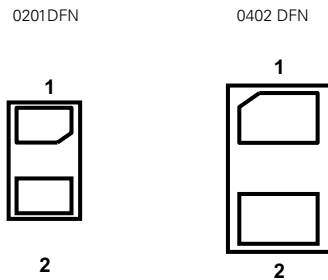
**THE DATASHEET OF
SESD0402X1BN-0015-096**



SESD Series Enhanced ESD Discrete TVS

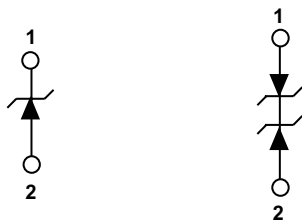


Pinout



Bottom View

Functional Block Diagram



Unidirectional

Bidirectional

Description

The SESD Series Enhanced ESD Discrete TVS provides ultra low capacitance unidirectional and bidirectional ESD protection for the world's most challenging high speed serial interfaces. Ultra low capacitance helps ensure excellent signal integrity on the most challenging consumer electronics interfaces, such as USB 3.1, HDMI 2.0, DisplayPort, Thunderbolt, and V-by-One®. Providing in excess of 22kV contact ESD protection (IEC61000-4-2) while maintaining extremely low leakage and dynamic resistance, offered in the industry's most popular footprints (0402 and 0201), the SESD series sets higher standards for signal integrity and usability.

Features

- 0.15pF TYP bidirectional
- 0.30pF TYP unidirectional
- ESD, IEC61000-4-2, ±22kV contact, ±22kV air
- Low clamping voltage of 14V @ $I_{pp}=2.5A$ (Bidirectional) ($t_p=8/20\mu s$)
- Low profile 0201 and 0402 DFN packages
- Facilitates excellent signal integrity
- ELV Compliant
- RoHS Compliant and Lead-free

Applications

- Ultra-high speed data lines
- USB 3.1, 3.0, 2.0
- HDMI 2.0, 1.4a, 1.3
- Thunderbolt
- DisplayPort™
- V-by-One®
- LVDS interfaces
- Consumer, mobile and portable electronics
- Tablet PC and external storage with high speed interfaces
- Applications requiring high ESD performance in small packages

Additional Information



[Datasheet](#)



[Resources](#)



[Samples](#)

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	2.5	A
T_{OP}	Operating Temperature	-55 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

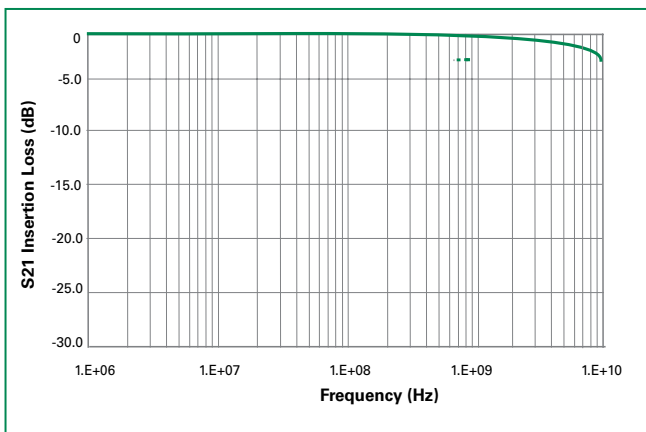
Unidirectional Electrical Characteristics - ($T_{OP}=25^\circ C$)

Parameter	Test Conditions	Min	Typ	Max	Units
Input Capacitance	@ $V_R = 0V$, $f = 3GHz$		0.30		pF
Breakdown Voltage	V_{BR} @ $I_T=1mA$		8.80		V
Reverse Working Voltage				7.0	V
Reverse Leakage Current	I_L @ $V_{RWM}=5.0V$		25		nA
Clamping Voltage	V_{CL} @ $I_{PP}=2.5A$		13.0		V
ESD Withstand Voltage	IEC61000-4-2 (Contact)	±22			kV
	IEC61000-4-2 (Air)	±22			

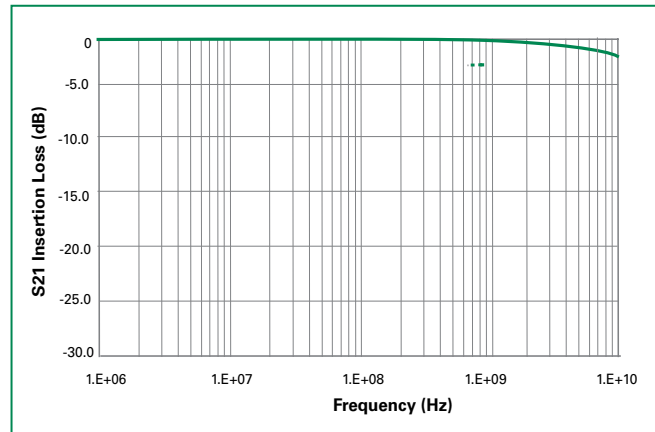
Bidirectional Electrical Characteristics - ($T_{OP}=25^\circ C$)

Parameter	Test Conditions	Min	Typ	Max	Units
Input Capacitance	@ $V_R = 0V$, $f = 3GHz$		0.15		pF
Breakdown Voltage	V_{BR} @ $I_T=1mA$		9.6		V
Reverse Working Voltage				7.0	V
Reverse Leakage Current	I_L @ $V_{RWM}=5.0V$		25		nA
Clamping Voltage	V_{CL} @ $I_{PP}=2.5A$		14.0		V
ESD Withstand Voltage	IEC61000-4-2 (Contact)	±22			kV
	IEC61000-4-2 (Air)	±22			

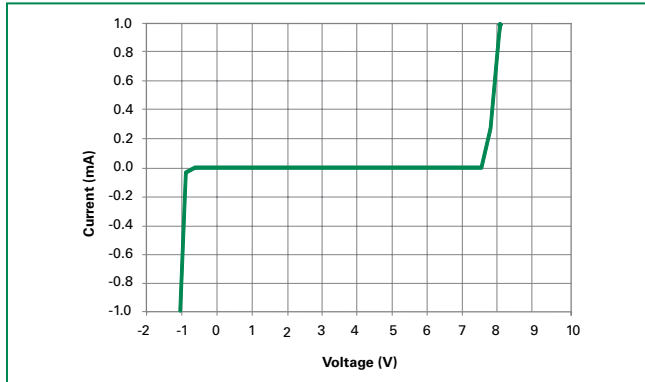
Insertion Loss Diagram - Unidirectional



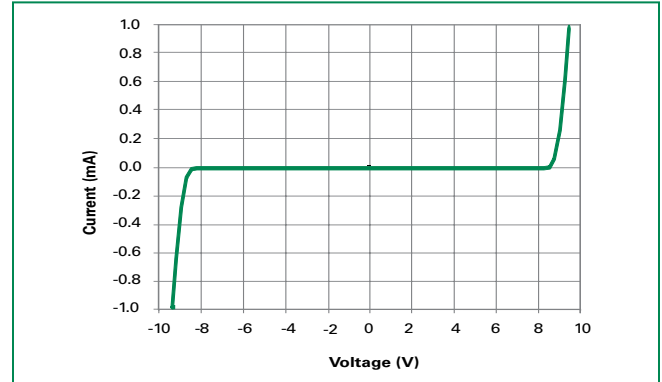
Insertion Loss Diagram - Bidirectional



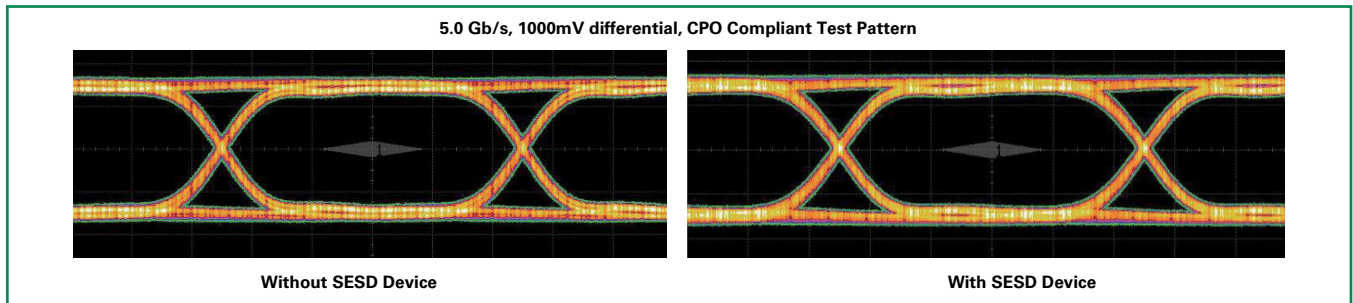
Device IV Curve - Unidirectional



Device IV Curve - Bidirectional

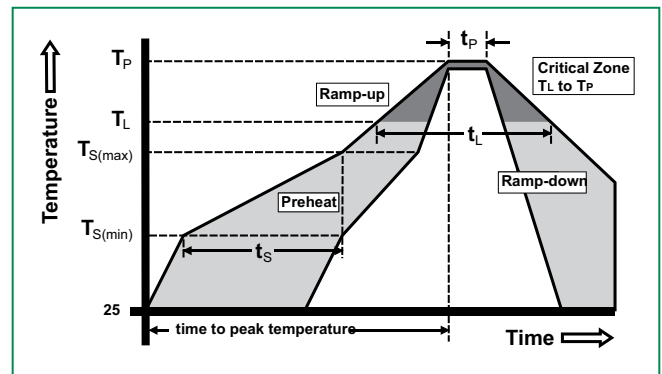


USB3.0 Eye Diagram



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

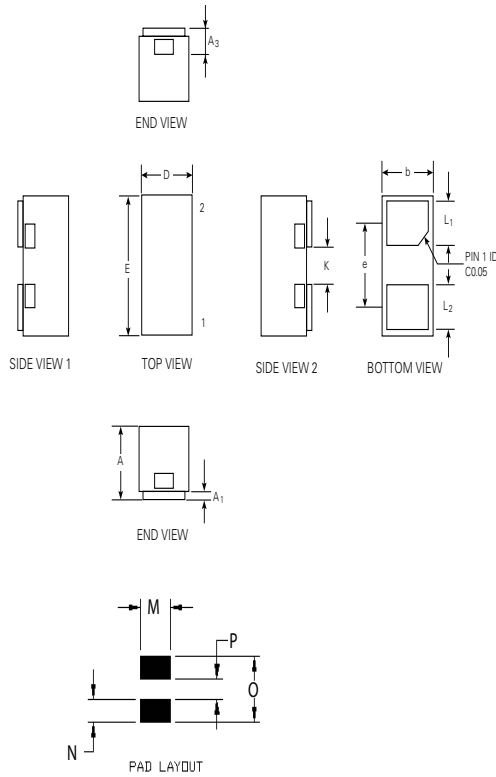


Product Characteristics of 0402 DFN Package

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substrate material	Silicon
Body Material	V-0 per UL 94 Molded Epoxy

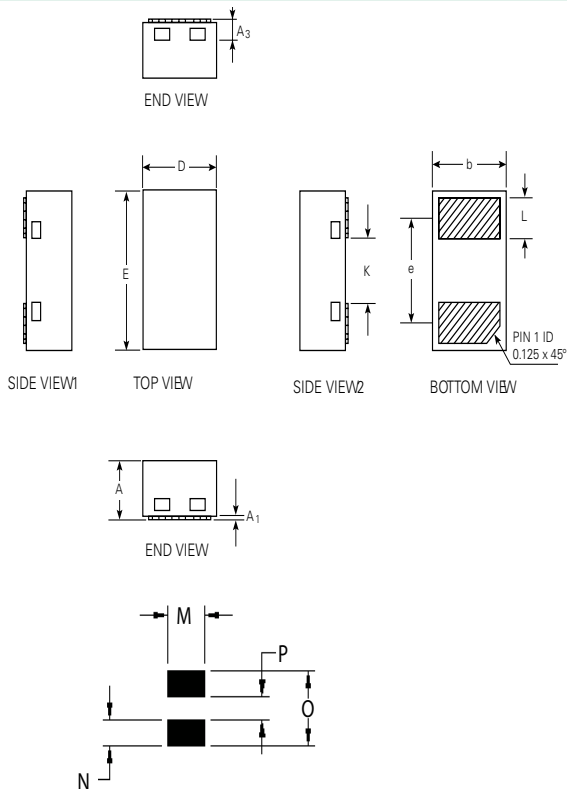
- Notes :
1. All dimensions are in millimeters
 2. Dimensions include solder plating.
 3. Dimensions are exclusive of mold flash & metal burr.
 4. Bto is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
 5. Package surface matte finish VDI 11-13.

Package Dimensions — 0201 DFN



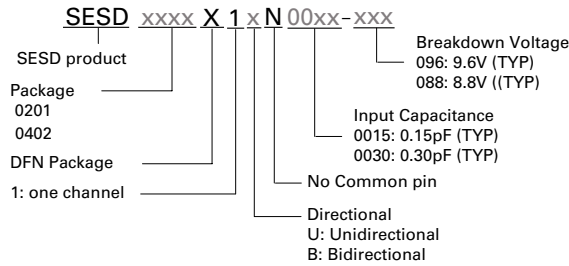
Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.28	0.30	0.32	0.011	0.012	0.013
A1	0	-	0.05	0	-	0.002
A3	0.102 ref.			0.004 ref.		
D	0.25	0.30	0.35	0.010	0.012	0.014
E	0.55	0.60	0.65	0.022	0.024	0.026
K	0.11	0.17	0.22	0.004	0.007	0.009
b	0.20	0.25	0.30	0.008	0.010	0.012
L1	0.13	0.18	0.23	0.005	0.008	0.009
L2	0.14	0.19	0.24	0.006	0.007	0.009
e	0.356 BSC			0.014 BSC		
M		0.32			0.013	
N		0.24			0.009	
O		0.62			0.024	
P		0.14			0.006	

Package Dimensions — 0402 DFN

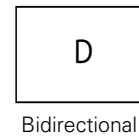
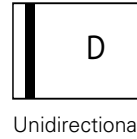


Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.33	0.38	0.43	0.013	0.015	0.017
A1	0	-	0.05	0	-	0.002
A3	0.13 ref.			0.005 ref.		
D	0.55	0.60	0.65	0.022	0.024	0.026
E	0.95	1.00	1.05	0.037	0.039	0.041
K	0.35	0.40	0.45	0.014	0.016	0.018
b	0.45	0.50	0.55	0.018	0.020	0.022
L	0.20	0.25	0.30	0.008	0.010	0.012
e	0.65 BSC			0.026 BSC		
M		0.60			0.024	
N		0.35			0.014	
O		1.00			0.039	
P		0.30			0.012	

Part Numbering System



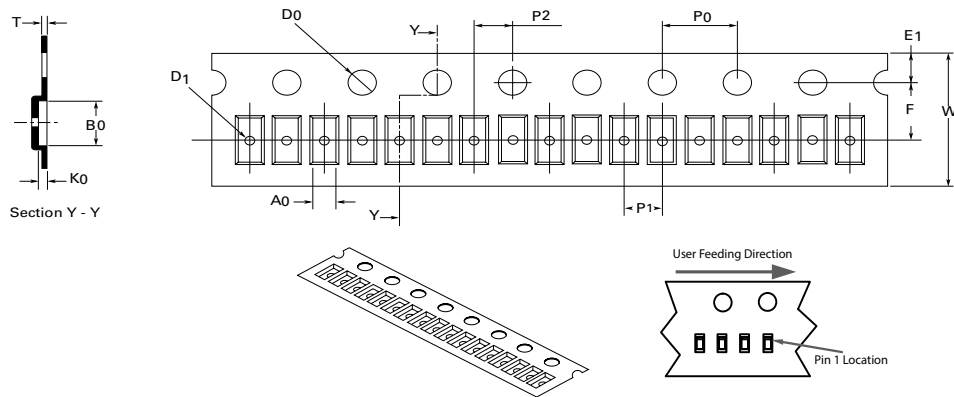
Part Marking System



Ordering Information

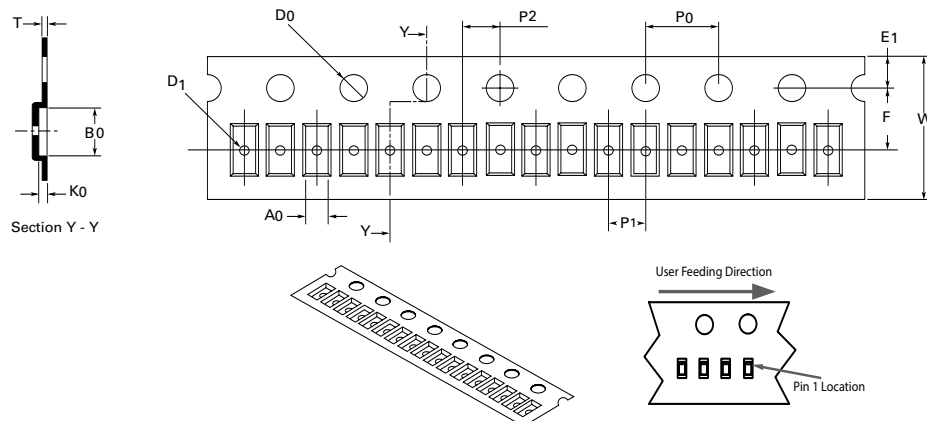
Part Number	Package	Marking	Ordering Part Number	Minimum Order Quantity
SESD0201X1UN-0030-088	0201 DFN	I D	RF3917-000	75000
SESD0201X1BN-0015-096	0201 DFN	D	RF3918-000	75000
SESD0402X1UN-0030-088	0402 DFN	I D	RF3920-000	50000
SESD0402X1BN-0015-096	0402 DFN	D	RF3922-000	50000

Embossed Carrier Tape & Reel Specification – 0201 DFN



Symbol	Millimeters
A0	0.36+/-0.03
B0	0.66+/-0.03
D0	∅ 1.50+ 0.10/-0
D1	∅ 0.20+/- 0.05
E1	1.75+/-0.10
F	3.50+/-0.05
K0	0.33+/-0.03
P0	4.00+/-0.10
P1	2.00+/-0.10
P2	2.00+/-0.05
W	8.00+/-0.10
T	0.23+/-0.02



Embossed Carrier Tape & Reel Specification – 0402 DFN



Symbol	Millimeters
A0	0.70+/-0.05
B0	1.15+/-0.05
D0	∅ 1.55 + 0.05
D1	∅ 0.40 +/- 0.05
E1	1.75+/-0.10
F	3.50+/-0.05
K0	0.47+/-0.05
P0	4.00+/-0.10
P1	2.00+/-0.10
P2	2.00+/-0.05
W	8.00+/-0.10
T	0.20+/-0.05

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View SESD0402X1BN-0015-096 on WIN SOURCE](#)
-  [Littelfuse Inc. Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management